

CLAIMS

What is claimed is:

1. An integrated circuit package, comprising:
a first die with a conductive side;
5 a plurality of lead posts, wherein the conductive side of the first die faces the plurality of lead posts; and
an encapsulating material encapsulating the first die and an end of the lead posts adjacent to the conductive side of the die.
- 10 2. The integrated circuit package, as recited in claim 1, wherein the conductive side of the first die is mechanically and electrically connected to the plurality of lead posts.
3. The integrated circuit package, as recited in claim 2, wherein the conductive side comprises a plurality of spaced apart conductive pads, which are mechanically and electrically
15 connected to the lead posts.
4. The integrated circuit package, as recited in claim 3, wherein the plurality of conductive pads is mechanically and electrically connected to the lead posts by conductive epoxy.
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5. The integrated circuit package, as recited in claim 2, wherein the lead posts have equal spacing and pitch.
6. The integrated circuit package, as recited in claim 2, wherein the lead posts have a
25 square cross section.
7. The integrated circuit package, as recited in claim 2, wherein the lead posts have a round cross section.
- 30 8. The integrated circuit package, as recited in claim 2, wherein the lead posts have lengths which are substantially perpendicular to the conductive side of the first die.

9. The integrated circuit package, as recited in claim 2, further comprising a second die with a conductive side and a side opposite the conductive side, wherein the side opposite the conductive side is connected to a side opposite the conductive side of the first die.

5 10. The integrated circuit package, as recited in claim 9, further comprising wirebonding connected between the conductive side of the second die and at least one lead post of the plurality of lead posts.

11. An integrated circuit package comprising:
 10 an array of lead posts that are equally spaced apart, each of the lead posts having an oversized contact pad on a bottom surface of the integrated circuit package, wherein each oversized contact pad has a diameter that is larger than a diameter of a respective lead post;
 a first die having a conductive side that is electrically and mechanically connected to at least some of lead posts within the array of lead posts, wherein the conductive side of the
 15 first die faces the lead posts; and
 an encapsulating material that encapsulates the first die.

12. An integrated circuit package as recited in claim 11 wherein the conductive side of each of the first dice is in direct contact with at least some of the lead posts.

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13. An integrated circuit package as recited in claim 11, further comprising:
 a second die that is attached to the first die, wherein the second die has a conductive side and a side opposite the conductive side, wherein the side opposite the conductive side of each second die is connected to a side opposite the conductive side of the first die, wherein
 25 the second die has a plurality of conductive pads on the conductive side of the second die; and
 interconnecting wires that connect the conductive pads of the second die to lead posts of the array of lead posts, wherein the encapsulating material also encapsulates the second die and each of the interconnecting wires.

30 14. An integrated circuit package as recited in claim 11 wherein the encapsulating material has a top and a bottom surface and wherein each of the oversized contact pads are formed on the bottom surface of the encapsulating material.

15. An integrated circuit package as recited in claim 11 wherein each of the oversized contact pads have a substantially square outline.